

CLAIMS:

1. A method for manufacturing a multi-layered ceramic electronic component by laminating a plurality of multi-layered units each formed by laminating a release layer, an electrode layer and a ceramic green
5 sheet on a support sheet in this order, the method comprising steps of positioning the multi-layered unit on a base substrate so that the surface of the ceramic green sheet is contact with an agglutinant layer formed on the surface of the base substrate in such a manner that the bonding strength between itself and the support substrate is higher than the
10 bonding strength between the support sheet and the release layer and lower than the bonding strength between itself and the ceramic green sheet, pressing it and laminating multi-layered units on the base substrate.
- 15 2. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer has a thickness of 0.01 μm to 0.3 μm .
3. A method for manufacturing a multi-layered ceramic electronic
20 component in accordance with Claim 1, wherein the agglutinant layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to.
4. A method for manufacturing a multi-layered ceramic electronic
25 component in accordance with Claim 2, wherein the agglutinant layer contains a binder belonging to the same binder group as that a binder contained in the ceramic green sheet belongs to.

5. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent group as that a plasticizing agent contained in the ceramic green sheet
5 belongs to.

6. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a plasticizing agent belonging to the same plasticizing agent
10 group as that a plasticizing agent contained in the ceramic green sheet belongs to.

7. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer
15 contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

8. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer
20 contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

9. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer
25 contains an ampholytic surfactant in an amount smaller than that of the binder.

10. A method for manufacturing a multi-layered ceramic electronic

component in accordance with Claim 2, wherein the agglutinant layer contains an ampholytic surfactant in an amount smaller than that of the binder.

5 11. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

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12. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and
15 polyethylene terephthalate.

13. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

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14. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the ceramic green sheet has a thickness equal to or thinner than 3 μm .

25 15. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1 which further includes steps of peeling off the support sheet from the release layer of the multi-layered unit laminated on the base substrate and further laminating a new

multi-layered unit in which an adhesive layer is formed on the surface of a ceramic green sheet onto the release layer of the multi-layered unit laminated on the base substrate via the adhesive layer.

5 16. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2 which further includes steps of peeling off the support sheet from the release layer of the multi-layered unit laminated on the base substrate and further laminating a new multi-layered unit in which an adhesive layer is formed on a ceramic
10 green sheet onto the release layer of the multi-layered unit laminated on the base substrate via the adhesive layer.

17. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the multi-layered unit
15 includes a spacer layer formed on the surface of the release layer in a complementary pattern to that of the electrode layer.

18. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the multi-layered unit
20 includes a spacer layer formed on the surface of the release layer in a complementary pattern to that of the electrode layer